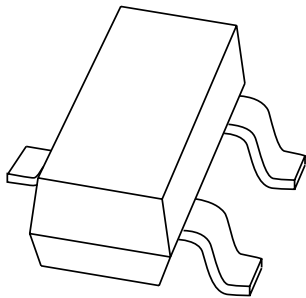


DATA SHEET



BAT54 series Schottky barrier (double) diodes

Product data sheet
Supersedes data of 2001 Oct 12

2002 Mar 04

Schottky barrier (double) diodes

BAT54 series

FEATURES

- Low forward voltage
- Guard ring protected
- Small plastic SMD package.

APPLICATIONS

- Ultra high-speed switching
- Voltage clamping
- Protection circuits
- Blocking diodes.

DESCRIPTION

Planar Schottky barrier diodes encapsulated in a SOT23 small plastic SMD package. Single diodes and double diodes with different pinning are available.

MARKING

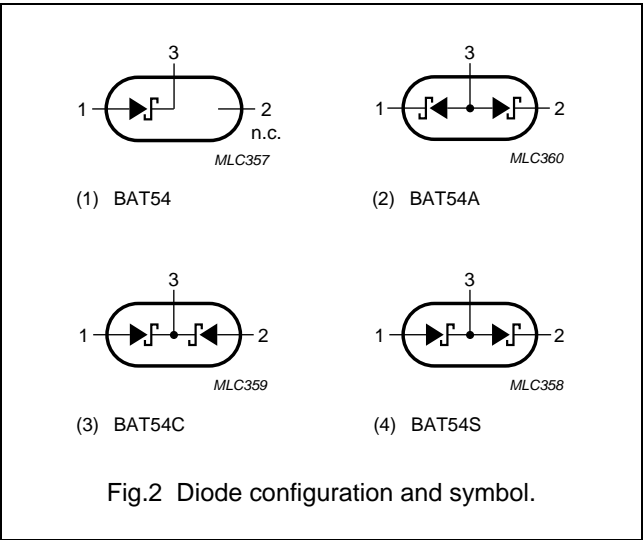
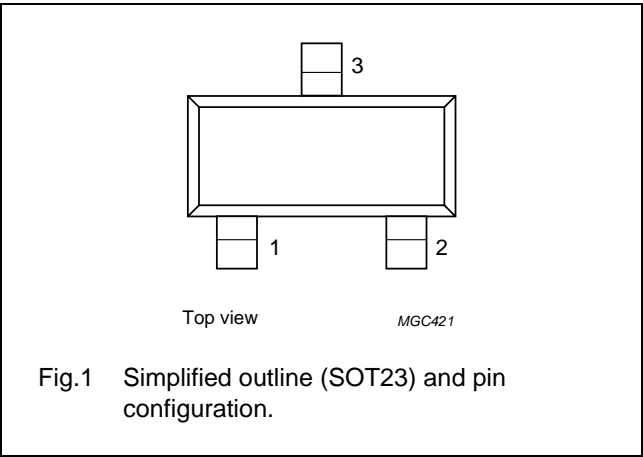
TYPE NUMBER	MARKING CODE ⁽¹⁾
BAT54	L4*
BAT54A	L42 or *V3
BAT54C	L43 or *W1
BAT54S	L44 or *V4

Note

1. * = p : Made in Hong Kong.
* = t : Made in Malaysia.
* = W: Made in China.

PINNING

PIN	DESCRIPTION			
	BAT54	BAT54A	BAT54C	BAT54S
1	a	k ₁	a ₁	a ₁
2	n.c.	k ₂	a ₂	k ₂
3	k	a ₁ , a ₂	k ₁ , k ₂	k ₁ , a ₂



Schottky barrier (double) diodes

BAT54 series

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
Per diode					
V_R	continuous reverse voltage		–	30	V
I_F	continuous forward current		–	200	mA
I_{FRM}	repetitive peak forward current	$t_p \leq 1 \text{ s}; \delta \leq 0.5$	–	300	mA
I_{FSM}	non-repetitive peak forward current	$t_p < 10 \text{ ms}$	–	600	mA
T_{stg}	storage temperature		–65	+150	°C
T_j	junction temperature		–	125	°C
Per device					
P_{tot}	total power dissipation	$T_{amb} \leq 25 \text{ °C}$	–	230	mW

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
$R_{th\ j-a}$	thermal resistance from junction to ambient	note 1	500	K/W

Note

1. Refer to SOT23 standard mounting conditions.

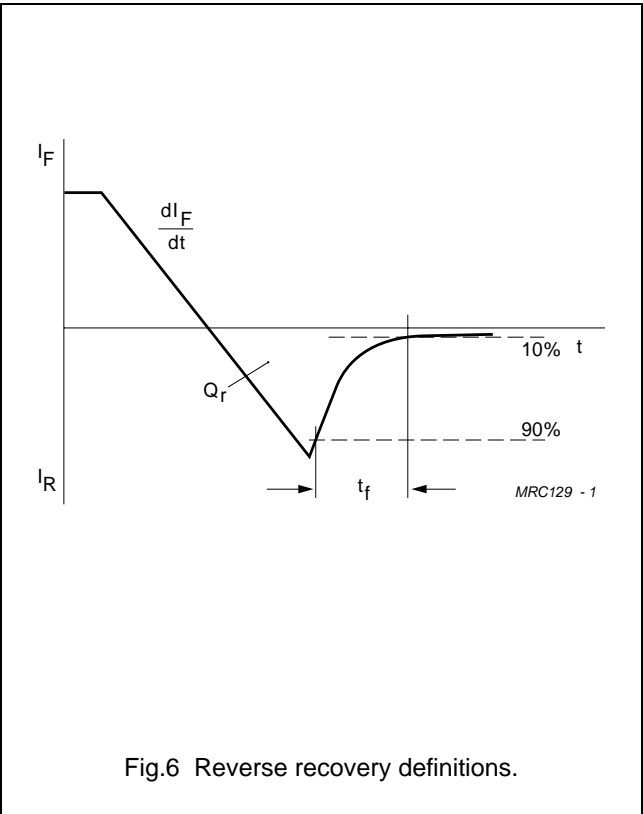
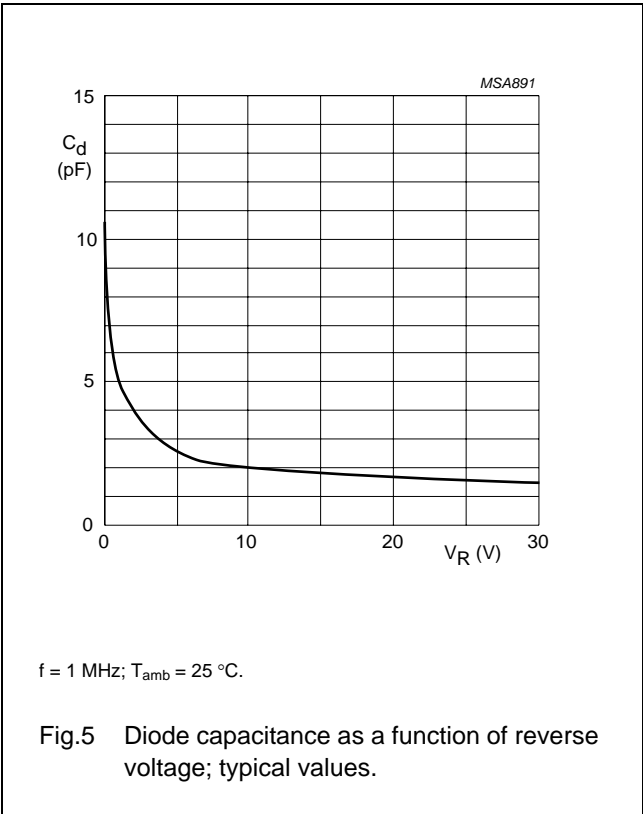
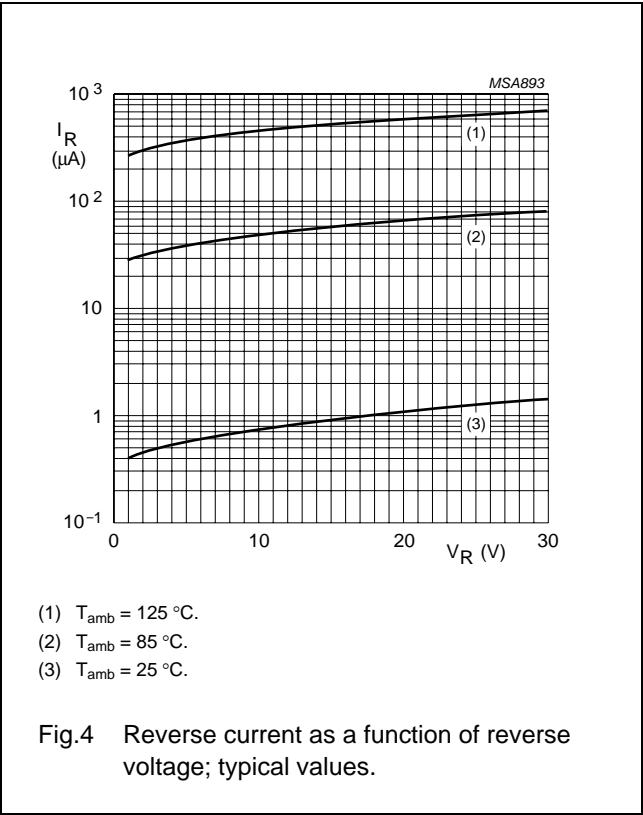
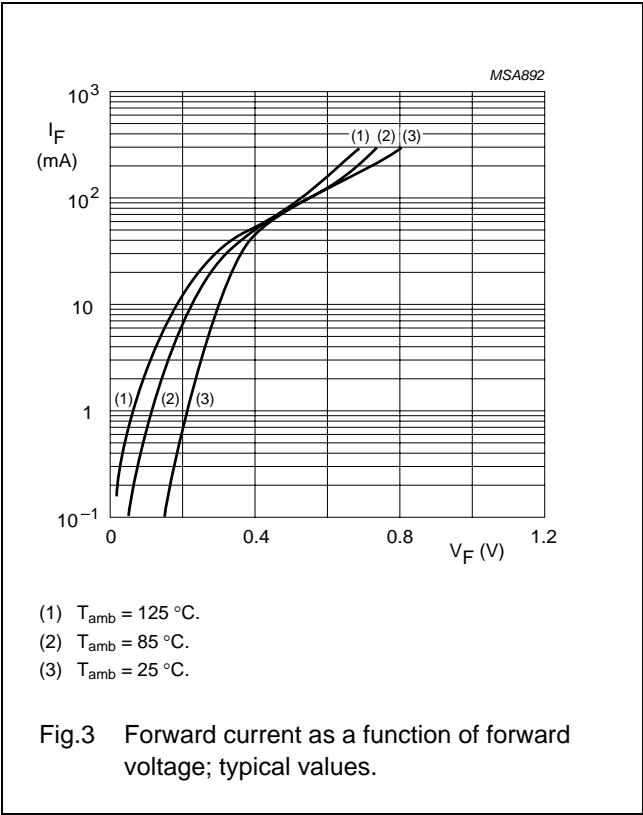
CHARACTERISTICS

$T_{amb} = 25 \text{ °C}$ unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MAX.	UNIT
Per diode				
V_F	forward voltage	see Fig.3 $I_F = 0.1 \text{ mA}$ $I_F = 1 \text{ mA}$ $I_F = 10 \text{ mA}$ $I_F = 30 \text{ mA}$ $I_F = 100 \text{ mA}$	240 320 400 500 800	mV mV mV mV mV
I_R	reverse current	$V_R = 25 \text{ V}$; see Fig.4	2	μA
t_{rr}	reverse recovery time	when switched from $I_F = 10 \text{ mA}$ to $I_R = 10 \text{ mA}$; $R_L = 100 \text{ }\Omega$; measured at $I_R = 1 \text{ mA}$; see Fig.6	5	ns
C_d	diode capacitance	$f = 1 \text{ MHz}$; $V_R = 1 \text{ V}$; see Fig.5	10	pF

Schottky barrier (double) diodes

BAT54 series



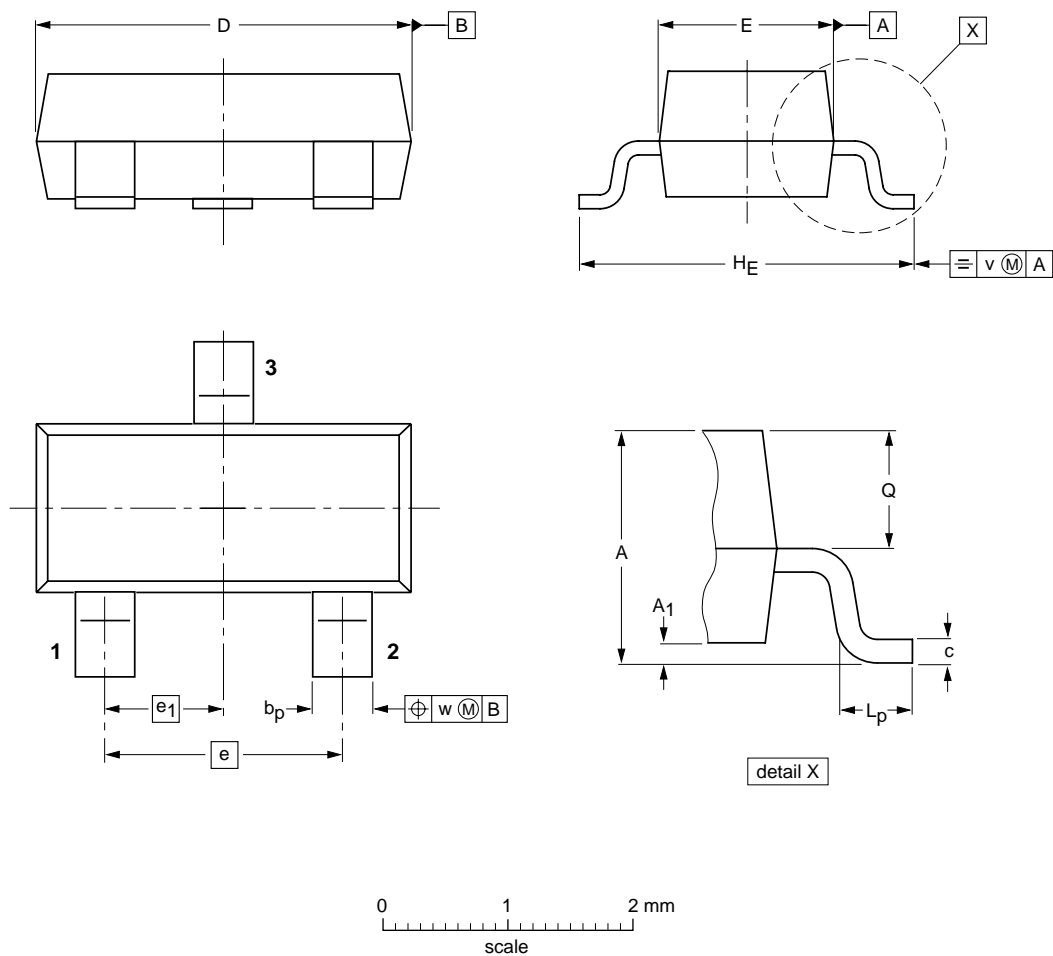
Schottky barrier (double) diodes

BAT54 series

PACKAGE OUTLINE

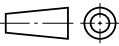
Plastic surface mounted package; 3 leads

SOT23



DIMENSIONS (mm are the original dimensions)

UNIT	A	A ₁ max.	b _p	c	D	E	e	e ₁	H _E	L _p	Q	v	w
mm	1.1 0.9	0.1	0.48 0.38	0.15 0.09	3.0 2.8	1.4 1.2	1.9	0.95	2.5 2.1	0.45 0.15	0.55 0.45	0.2	0.1

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT23		TO-236AB				97-02-28 99-09-13

Schottky barrier (double) diodes

BAT54 series

DATA SHEET STATUS

DOCUMENT STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

Notes

1. Please consult the most recently issued document before initiating or completing a design.
2. The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

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